

IN THE CLAIMS:

Please amend claims 14-16 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-13. (Cancelled)

14. (Currently Amended) A method of forming a 8-layer printed circuit board (PCB) comprising the steps of:

5 preparing a core (1) including a thin compound plate having an inner layer (101) made of a prepreg material and two copper clad layers (102) provided on two outer sides of the inner layer (101);

performing a circuit formation on the two copper clad layers (102) forming part of the core (1) by way of etching to form two circuit layers (1a, 1b) on the two outer sides of the inner layer, respectively;

10 ~~laminating a dielectric layer to form~~ forming a laminated dielectric layer (2) from the prepreg material and a copper clad layer (3) are sequentially formed on each of the two circuit layer (1a, 1b) ~~by way of lamination~~, so that a four-layer PCB is formed;

15 ~~forming a circuit~~ another two circuit layers (3a, 3b) on the copper clad layers (3) to form the ~~the~~ another two circuit layers (3a, 3b) on outer sides of the two dielectric layers (2);

20 forming two resin layers (4) being separately formed with a resin build-up process through liquid epoxy coating or dry film type epoxy laminating on the two circuit layers (3a, 3b) by way of applying a dielectric material and epoxy on outer sides of the two circuit layers (3a, 3b);

forming necessary conductive holes (4a, 4b) on the resin layers (4) by performing laser drilling and mechanical drilling, respectively, to form a PCB;

plating the PCB with copper to form a copper-plating layer (5) on all outer surfaces of the PCB;

25 performing the circuit formation by way of etching the copper-plating layer (5) to form two additional circuit layers; and

forming another two laminating dielectric layers (6) from the prepreg material, and another two copper clad layers (7) being sequentially formed on outer sides of the two additional circuit layers (5a, 5b) by way of lamination to form the 8-layer PCB,

wherein the 8-layer PCB has only 8 layers.

15. (Currently Amended) The method of claim 14, further comprising performing operations, selected from the group consisting of window formation, laser drilling, plating, and etching,

wherein the operations are performed on the copper clad layers (7) to form other circuit layers (7a, 7b) on outer sides of the two laminating dielectric layers (6).

16. (Currently Amended) The method of claim 15, further comprising performing further operations, selected from the group consisting of applying solder mask (8), applying plating gold, and spraying tin,

wherein the further operations are performed on the two other circuit layers to complete the eight-layer PCB.

17. (Previously Presented) The method of claim 14, wherein the prepreg material is a resin-impregnated fiberglass fabric.